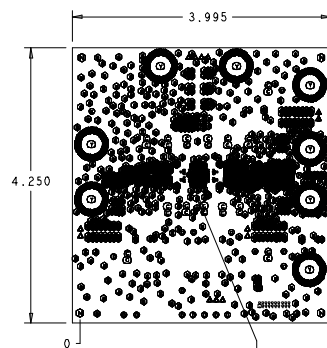


NOTES: UNLESS OTHERWISE SPECIFIED.

- BOARD IS VIEWED FROM LAYER 1 (PRIMARY SIDE). TOTAL CONDUCTOR LAYERS ARE 6.
- THIS DRAWING ALSO EXISTS ON ELECTRONIC MEDIA.
- MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE. ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS DIRECTIVE 2002/95/EC LAMINATE AND RESIN MATERIAL PARAMETERS
Tg > 170 C
Td > 294 C
- FINISH:
ELECTROLISS NICKEL/GOLD(ENIG)PLATING IS TO BE USED. 3-8 uin GOLD OVER 100uin NICKEL.
- SOLDERMASK SHALL BE LPI (BLUE) OVER BARE COPPER, 0.0005"-0.002" THICK, AND CONFORM TO THE LATEST REVISION OF IPC-SM-840.
- CONDUCTOR WIDTH AND SPACING:
THE NOMINAL CONDUCTOR WIDTH AND SPACING ON FINISHED BOARD IS:
WIDTH 0.004"
SPACING 0.004"
- SILKSCREEN SHALL BE WHITE NONCONDUCTIVE EPOXY INK, AND SHALL NOT APPEAR ON ANY PADS OR MOUNTING HOLES.
- PRIOR TO BOARD FABRICATION, COMPARE GERBER DATA TO SUPPLIED IPC-D-356A NET LIST. REPORT ALL DISCREPANCIES.
- VIAS IN PADS MUST BE FILLED USING CONDUCTIVE EPOXY.



SURFACE OF THIS VIAS IN PADS FOR WLCSP MUST BE FLAT AFTER PLATING.
COPPER FILLED OR PLATE SHUT & PLATE OVER.

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	6.0	PLATED	48
⊙	8.0	PLATED	69
⊙	8.0	PLATED	1503
•	23.0	PLATED	19
•	23.0	PLATED	1
•	40.0	PLATED	17
⊙	40.0	PLATED	14
⊙	40.0	PLATED	14
Δ	40.0	PLATED	10
Δ	41.0	PLATED	3
⊙	100.0	PLATED	2
⊙	255.0	PLATED	8
⊙	128.0	NON-PLATED	4

DRILL CHART: TOP to L2			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	4.0	PLATED	33
•	6.0	PLATED	202

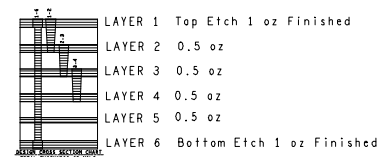
COPPER FILLED
COPPER FILLED

DRILL CHART: L2 to L3			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	4.0	PLATED	44

COPPER FILLED

DRILL CHART: L3 to L4			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	6.0	PLATED	45

COPPER FILLED



Drawn By: MARGARET SAVIEO	Date Drawn: 11/07/17	Engineer: ZHIGANG LIANG
Released By:	Date Released:	ISL91212AII-EVZ Fabrication Drawing
Updated By:	Date Updated: 01/09/19	MAX6 N/A MIN6 N/A REV. A
		FILENAME: ISL91212AII-EVZ REVA SHEET 1 of 1